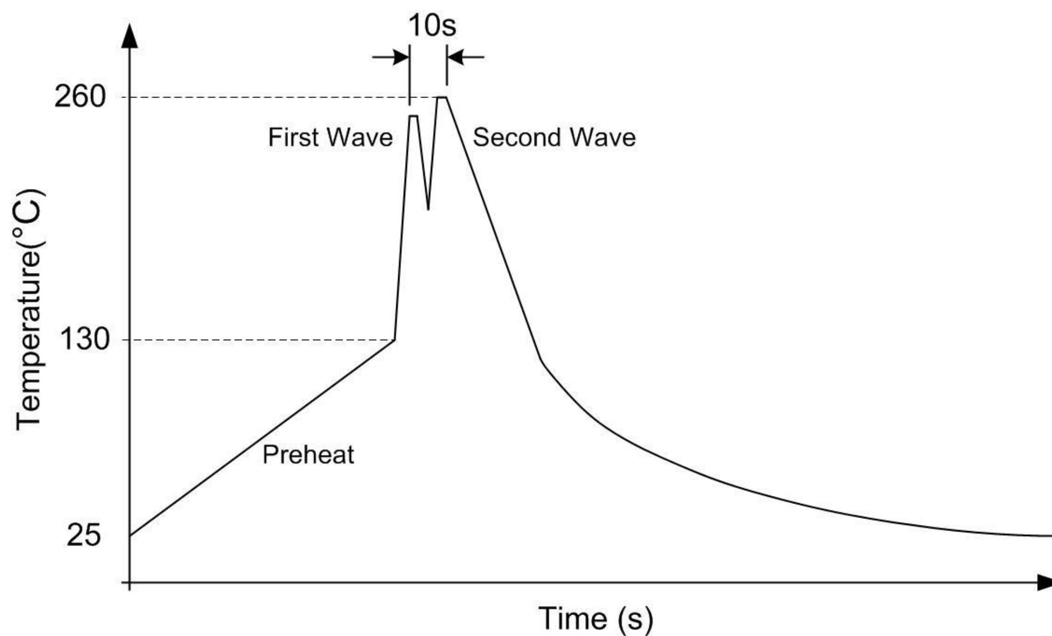
Recommended Solder Reflow Profile

Recommended Soldering Profile (Through hole parts)

Wave Soldering Profiles (Refer to BS CECC 00802)	
Profile Feature	**Lead-free Assembly**
Heating rate during preheat	1-2 °C/second
Ramp-up rate	200 °C/second max.
Recommended peak temperature	260 ºC
Time within +0°C / -5°C of peak temperature	10 seconds max.
Ramp-down rate	5 ºC/s max.



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Recommended Soldering Profile (SMD parts)

Reflow Soldering Profiles (Refer to IPC/JEDEC J-STD-020)	
Profile Feature	**Lead-free Assembly**
Preheat/Soak Temperature Min (T_{smin}) Temperature Max (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	 150ºC 200ºC 60-120 seconds
Ramp-up rate (T_L to T_p)	3 ºC/second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	200ºC 60-150 seconds
Peak package body temperature (T_p)	See Table1
Time (tp) within 5°C of T_p	10 seconds
Ramp-down rate (T_p to T_L)	6 ºC/second max.
Time 25 °C to peak temperature	8 minutes max.

Table1 - Peak package body temperature (T_p)			
Package Thickness	Volume mm^3 < 350	Volume mm^3 = 350 ~ 2000	Volume mm^3 > 2000
< 1.6mm	260°C	260°C	260°C
1.6 mm - 2.5 mm	260°C	250°C	245°C
> 2.5mm	250°C	245°C	245°C